



Materials Declaration Form


IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2025-07-04
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Authorized Representative *	MDG MD CHAMPION
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement	
	<p>While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.</p>
Legal Statement	
Supplier Acceptance *	true
	Legal Declaration *
	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST25R500-HQWT	ULIC*D5001MB	A	993N	2025-07-04
	Amount	UoM	Unit type	ST ECOPACK Grade
	67.61	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	5X5X1.0mm	32	No lead	
Comment	Package : B04R VFQFPN 5X5X1 32L WETTABLE FLANKS DM00384332			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2024				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	ULIC*D5001MB				6000001.0	999999.5
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	2.783	mg	supplier	die	Silicon (Si)	7440-21-3		2.665	mg	957600	39417
				supplier	metallization	Aluminium (Al)	7429-90-5		0.014	mg	5031	207
				supplier	metallization	Copper (Cu)	7440-50-8		0.047	mg	16888	695
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.017	mg	6109	251
				supplier	Passivation	Silicon Nitride	12033-89-5		0.009	mg	3234	133
				supplier	Passivation	Silicon Oxide	7631-86-9		0.031	mg	11139	459
Leadframe_EFTEC64T Ag	Copper & its alloys	21.124	mg	Supplier	Alloy	Cu	7440-50-8		20.552	mg	972944	303986
					Alloy	Cr	7440-47-3		0.056	mg	2646	827
					Alloy	Sn	7440-31-5		0.052	mg	2450	765
					Alloy	Zn	7440-66-6		0.041	mg	1960	612
					coating	Ag	7440-22-4		0.422	mg	20000	6249
Die Attach -8600	M-011 Other inorganic materials	4.597	mg	Supplier	Glue	Silver >= 99,9 % Ag as powder	7440-22-4		3.747	mg	815000	55414
					Glue	(Octahydro-4,7-methano-1H-indenediyl)bis(m	42594-17-2		0.276	mg	60000	4080
					Glue	exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl me	7534-94-3		0.276	mg	60000	4080
					Glue	Isobornyl acrylate	5888-33-5		0.276	mg	60000	4080
					Glue	2-(3,4-Epoxy cyclohexyl)ethyltrimethoxysilane	3388-04-3		0.023	mg	5000	340
Bonding wire- Au wire	M-011 Other inorganic materials	0.348	mg	Supplier	Bonding wire	Au	7440-57-5		0.345	mg	992000	5106
						Pt	7440-06-4		0.002	mg	6000	31
						Pd	7440-05-3		0.001	mg	2000	10
Encapsulation - G700LTD	M-011 Other inorganic materials	36.597	mg	Supplier	Molding compound	Epoxy Resin	Trade secret		1.830	mg	50000	27065
						Phenol Resin	Trade secret		0.988	mg	27000	14615
						Silica (Amorphous)A	60676-86-0		31.839	mg	870000	470927
						Silica (Amorphous)B	7631-86-9		1.830	mg	50000	27065
						Carbon Black	1333-86-4		0.110	mg	3000	1624
External plating-Tin	M-011 Other inorganic materials	2.161	mg	Supplier	External plating	Sn	7440-31-5		2.161	mg	1000000	31963